16 IDEA Inspection Process Guidelines Checklist



IDEA Inspection Process Guidelines Checklist

This checklist shall be used in conjunction with all requirements stated in IDEA-STD-1010 and ANSI/ESD S20.20

www.IDofEA.org Page 1 of 2 **General Carton Inspection** Inspection of Carrier (Section 10.1.5.1) (Section 10.1.5.4) Weigh product contents and record Read and record status of Humidity Indicator Card (HIC). To test card for ☐ Inspect outer package for evidence of damage validity, see J-STD-033 for HIC test. Photograph/record any findings Inspect the sealing tape for evidence of Tubes: tampering ☐ If factory packaged, verify tubes are imprinted with manufacturer name/ If damage or evidence of tampering is present note findings and alert vendor and carrier for a Verify all tubes are the same length and look clean and new (not yellowed possible freight claim or excessively scratched) Verify parts in the tube are all oriented the same direction Verify quantity of parts in tubes is consistent Verify all tubes have stoppers and they are the same in each tube Reels: □ Verify labels and label placement Outer Product Carton Inspection Scan and verify that barcode scan and printed information on label are (Section 10.1.5.2) consistent with each other ☐ Inspect package for any signs of damage or Verify that size of reel and the material (paper/plastic) match manufacturer signs of being opened spec sheet Photograph contents while in box if they exhibit Verify factory reel has proper leader tape damage, tampering, or nonconformance ☐ Verify reel count (no empty pockets) and cover film is properly attached Photograph labels and sealing tape if they exhibit damage, tampering, or nonconformance Compare part orientation in tape with manufacturer spec sheet and verify the parts oriented in the tape are consistent Inspect sealing tapes Inspect labels and verify data Verify that there are no splices or cuts in the tape Examine the box and compare with Trays: manufacturer's website or golden sample Verify the color and width of the banding is what is expected Scan barcode to verify information is readable Note if the banding has any preprinted markings Verify that the trays are oriented the same way Verify that there is a top tray to protect the parts ☐ Verify and record if covered by cardboard and verify if cardboard is antistatic Verify the chips' orientation in the tray is consistent with no missing pieces Inner Contents Inspection Verify and record date/lot code of parts (Section 10.1.5.3) Verify that the date/lot code match outside packaging/label on the box, if ☐ Inspect inner contents, packaging, bag seal and labels; photograph if they exhibit damage, tampering, or nonconformance Bulk: Inspect bag seal Verify count Compare inner labels with outer carton labels ☐ Verify the bag is correct for the type or parts received, (i.e., ESD or MBB) and photograph ☐ Verify any mfg markings on the bag against manufacturer spec sheet Verify bag seal date with product date code ☐ Scan the bar code to verify the information is Scan and verify that barcode scan and printed information on label are readable and matches the product consistent with each other identification: record results Verify and record date/lot codes Verify the product is properly packaged for the required Moisture Sensitivity Level (MSL) and compare the MSL level with datasheet Verify the package is ESD compliant

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Initial Inspection (Section 10.2.1)

Verify the part number, manufacturer and quantity match the purchase order and packing slip

☐ Verify that there is an original factory label; ensure there is not a label over label

Confirm the manufacturer's logo is printed on the label; inspect the spelling; the label should not be capable of being smudged

Verify and record the country of origin, date codes, and lot codes and ensure they are consistent throughout the packaging

Confirm the date code meets any restrictions specified on the purchase agreement

Record any signs of damage to the product or packaging

Note: Refer to IDEA-STD-1010-B Section 10.2.1.4 for additional information on inspecting discrete components.



Detailed Inspection (Visual) (Section 10.3.1)



☐ Verify the logo and markings match the manufacturer's specifications

☐ Confirm the markings are clear and do not appear to be re-marked or re-stamped

Confirm the markings are consistent throughout the package type from part to part and on the top and bottom of the parts (placement, font type, color, and texture)

Inspect laser marks for burn holes caused by aftermarket laser equipment

☐ Inspect for inconsistencies in package indents shape, size and locations

Confirm that there are no burn or blister marks, or evidence of exposure to excessive heat

☐ Ensure there are no colored dots or ink marks on the tops of components indicating previous testing or programming, unless allowed or required by the purchase order.

☐ Look for flux or chemical residue and and tool marks or heat-sink markings indicating refurbished parts

 $oldsymbol{\square}$ Confirm there are no cracks on the surface of the parts

☐ Verify the lead/pin count and formation or type of lead (DIP, SMB, Gull Wing, etc.) match the datasheet

Verify pins or terminal layout/count match manufacturer specs

Inspect for damaged leads (bent, scratched, broken, dented, missing, coplanarity, etc.) indicating the part has been salvaged or mishandled

Ensure that leads are not oxidized, re-tinned with solder (re-balled for BGAs), show signs of corrosion, or contamination from foreign substances

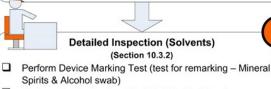
Look for leads that are too shiny for older date codes or too dull for new date codes; the pins should be similar in gloss or shine, color, and texture

Confirm there are no scratches on the inside and outside of leads; scratches under the BGA spheres are typically a sign of re-balled

Inspect BGAs, LGAs, and any terminals, lugs, or connectors to ensure that the component has not been used, refurbished, mishandled or contaminated

Photograph markings front and back for records

If nonconforming, document and photograph nonconformance(s)



Detailed Inspection (The Mechanical Inspection)



Perform Device Surface Test (test for blacktopping -Acetone swab)

Perform Scrape Test (as needed)

(Section 10.3.3)

Determine the min/max or acceptable tolerance range of each measurement being taken from the mfr datasheet Measure, verify and record the package dimensions

Measure for Thickness Variation

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